

ABSTRACT

A light emitting element (100) comprising an element chip (100C) provided, at least in a partial section in the thickness direction thereof, with a part of reduced cross-section where the cross sectional area decreases continuously or stepwise in the direction perpendicular to the thickness direction from the first major surface side toward the second major surface side. A part of a molded section (25) has a first mold layer (26) covering at least the part of reduced cross-section, and a second mold layer (25m) covering the outside of the first mold layer (26), wherein the first mold layer (26) is composed of a polymer mold material softer than that of the second mold layer (25m). A light emitting element, having such a structure that the element chip bonded onto a metal stage is not stripped easily even if mold resin expands, is thereby provided.